2SK763, 2SK763A

Silicon N-channel Power F-MOS FET

■ Features

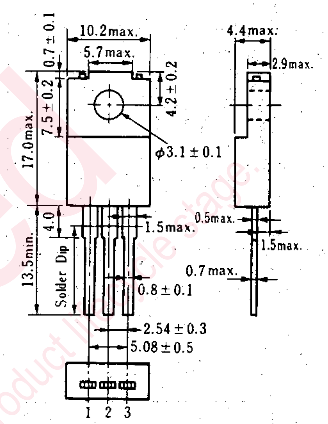
- Low ON resistance R_{DS} (on) : R_{DS} (on) = 0.9Ω (typ.)
- High switching rate : t_f = 50ns (typ.)
- No secondary breakdown
- High breakdown voltage

■ Application

- No contact relay
- Solenoid drive
- Motor drive
- Control equipment
- Switching power source

■ Package Dimensions

Unit: mm



1 : Gate
2 : Drain
3 : Source

TO-220 full pack package (a type)

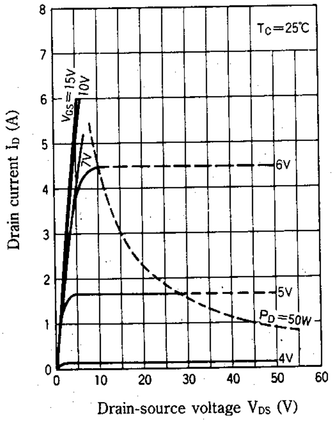
■ Absolute Maximum Ratings (Tc=25°C)

Item		Symbol	Value	Unit
Drain-source voltage	2SK763	V_{DSS}	400	V
	2SK763A		450	
Gate-source voltage		V_{GSS}	±20	V
Drain current	DC	I_D	5	A
	Peak-to-peak value	I_{DP}	10	
Power dissipation	Tc=25℃	P_D	50	W
	Ta=25℃		2.0	
Channel temperature		T_{ch}	150	℃
Storage temperature		T_{stg}	−55~+150	℃

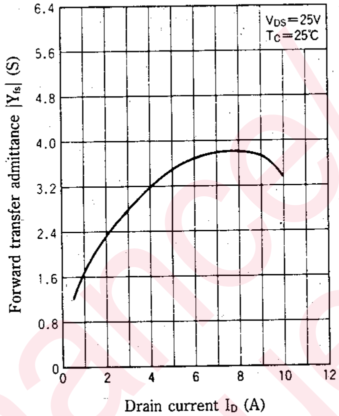
■ Electrical Characteristics (Tc=25°C)

Item		Symbol	Condition	min.	typ.	max.	Unit
Drain current		I_{DSS}	V_{DS}=320V, V_{GS}=0			0.1	mA
Gate-source current		I_{GSS}	V_{GS}=±20V, V_{DS}=0			±1	μA
Drain-source voltage	2SK763	V_{DSS}	I_D= 1 mA, V_{GS}=0	400			V
	2SK763A			450			
Gate threshold voltage		V_{th}	V_{DS}=25V, I_D=1mA	1		5	V
Drain-source ON resistance		R_{DS}(on)	V_{GS}=10V, I_D=3A		0.9	1.4	Ω
Forward transfer admittance		|Yfs|	V_{DS}=25V, I_D=3A	1.8	3.0		S
Input capacitance		C_{iss}	V_{DS}=20V, V_{GS}=0, f=1MHz		600		pF
Output capacitance		C_{oss}			140		pF
Reverse transfer capacitance		C_{rss}			60		pF
Turn-on time		t_{on}	V_{GS}=10V, I_D=3A, V_{DD}=150V, R_L=50Ω		40		ns
Fall time		t_f			50		ns
Delay time		t_d(off)			120		ns

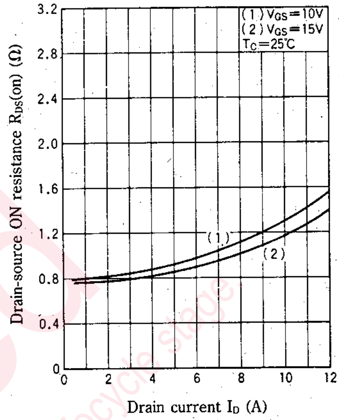
$I_D - V_{DS}$



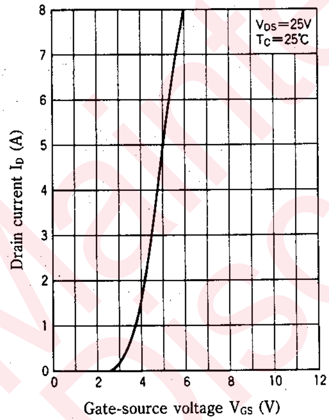
$|Y_{fs}| - I_D$



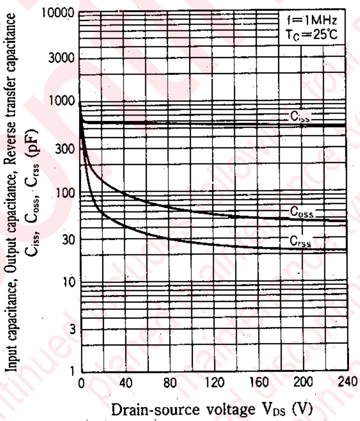
$R_{DS}(on) - I_D$



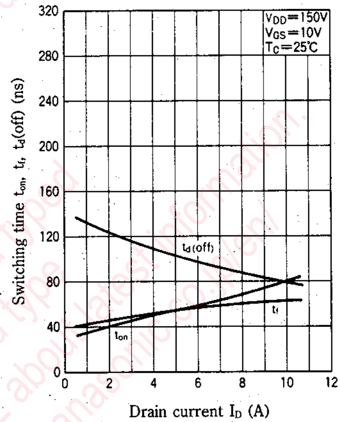
$I_D - V_{GS}$



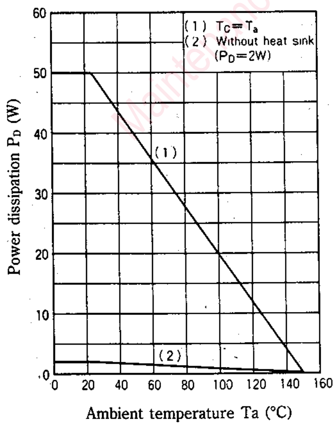
$C_{iss}, C_{oss}, C_{rss} - V_{DS}$



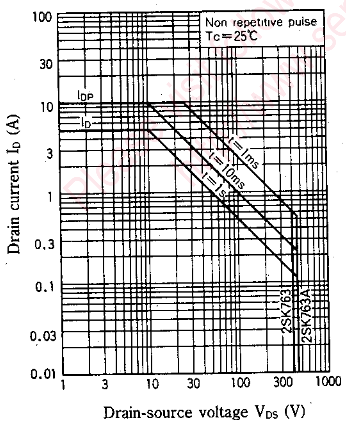
$t_{on}, t_f, t_d(off) - I_D$



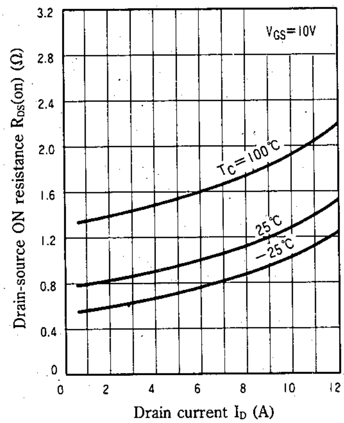
$P_D - Ta$



Safety operation area (ASO)



$R_{DS}(on) - I_D$



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